

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 28 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A method ~~and apparatus~~ for balancing layer-caused compressive or tensile stress in a semiconductor die, die wafer or similar substrate uses a stress-balancing layer (SBL) attached to the opposite side from the stress-causing layer before the die or wafer is significantly warped are provided. The SBL may also serve as, or support, an adhesive layer for die attach and be of a markable material for an enhanced marking method.